



SHEET 1 OF 1

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 247561US2	SERIAL NO. 10/754,539		
LIST OF REFERENCES CITED BY APPLICANT		APPLICANT Takuji MATSUMOTO, et al.					
		FILING DATE January 12, 2004		GROUP			
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION		
<i>Al</i>	AO	10-209167	08/07/1998	JAPAN (with English extract)	YES	NO	
	AP						
	AQ						
	AR						
	AS						
	AT						
	AU						
	AV						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
<i>Al</i>	AW	Y. HIRANO, et al., IEEE International SOI Conference, pages 131-132, "BULK-LAYOUT-COMPATIBLE 0.18 μ m SOI-CMOS TECHNOLOGY USING BODY-FIXED PARTIAL TRENCH ISOLATION (PTI)", October 1999					
<i>Al</i>	AX	S. MAEDA, et al., Symposium on VLSI Technology Digest of Technical Papers, pages 154-155, "IMPACT OF 0.18 μ m SOI CMOS TECHNOLOGY USING HYBRID TRENCH ISOLATION WITH HIGH RESISTIVITY SUBSTRATE ON EMBEDDED RF/ANALOG APPLICATIONS", 2000					
<i>Al</i>	AY	Y. HIRANO, et al., IEEE, IEDM, pages 467-470, "IMPACT OF 0.10 μ m SOI CMOS WITH BODY-TIED HYBRID TRENCH ISOLATION STRUCTURE TO BREAK THROUGH THE SCALING CRISIS OF SILICON TECHNOLOGY", 2000					
<i>Al</i>	AZ	S. MAEDA, et al., Extended Abstracts of the 2001 International Conference on Solid State Devices and Materials, pages 270-271, "A HIGHLY RELIABLE 0.18 μ m SOI CMOS TECHNOLOGY FOR 3.3V/1.8V OPERATION USING HYBRID TRENCH ISOLATION AND DUAL GATE OXIDE", 2001					<input type="checkbox"/> Additional References sheet(s) attached
Examiner <i>Andy Kline</i>					Date Considered 05/03/05		
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							